Subject: T1E1 Bonding Standardization

To: Mr. Howard Frazier, Chairman, IEEE 802.3ah (EFM)
Email: millardo@dominetsystems.com
CC: Ed Eckert, T1E1 Chair
Massimo Sorbaro, T1E1.4 Chair
Tom Starr, T1E1.4 Vice-chair

Dear Mr. Frazier,

During our San Diego meeting of 12/8/2003-12/11/2003, we progressed three bonding standards to letter ballot. The three bonding standards are targeted at ATM, Ethernet, and TDM applications. The Ethernet bonding standard is based heavily on the work of the IEEE 802.3ah task force, and generalizes the TPS-TC defined in Clause 61 for 10PASS-TS and 2BASE-TL to alternate DSL technologies.

We would like to solicit your advice on how to best cooperate on expanding the scope of the IEEE 802.3ah bonding techniques to other xDSL flavors. In particular, we are investigating two options for utilizing the methods defined in IEEE 802.3ah. In the first option, we would reproduce the methods and techniques of Clause 61 in our own standard. In the second option, we would reference the IEEE 802.3ah standard and note the changes and exceptions required for more general operation. We would appreciate your feedback on the best methods for cooperative development.

Additionally, for your information, the handshake techniques defined in IEEE 802.3ah for discovering which pairs are in a bonded group have been proposed for use in both the Ethernet and TDIM bonding standards being developed within T1E1.4.

I look forward to our continuing cooperation on developing standards. Please see the Ethernet bonding contribution (ftp://ftp.t1.org/T1E1/E1.4/DIR2003/3E142850.doc) and TDIM bonding contribution (ftp://ftp.t1.org/T1E1/E1.4/DIR2003/3E142711.zip) for more details. Should you desire additional information, please feel free to contact me.

Regards,

Rick Townsend, Chair of T1E1